

Listing of the Claims:

Claim 1 (original): A layered composition of a Cu-containing ceramic superconductor layer and a Ag-containing layer having between about 0.1 and about 0.3 atom percent Cu.

Claim 2 (original): The layered composition of claim 1, wherein the Cu-containing ceramic superconductor is a member of the YBCO family.

Claim 3 (original): The layered composition of claim 1, wherein the Cu-containing ceramic superconductor is a member of the BSCCO family.

Claim 4 (original): The layered composition of claim 1, wherein the Cu-containing ceramic superconductor is a member of the TBSCCO family.

Claim 5 (original): The layered composition of claim 1, wherein the Cu-containing ceramic superconductor is a member of the HBSCCO family.

Claim 6 (original): The layered composition of claim 1, wherein the Ag-containing layer is a substrate.

Claim 7 (original): The layered composition of claim 1, wherein the Ag-containing layer is a biaxially aligned or a non-biaxially aligned substrate.

Claim 8 (original): The layered composition of claim 1, wherein the Ag-containing layer is a stabilizer.

Claim 9 (original): The layered composition of claim 1, wherein the Ag-containing layer is a sheath.

Claim 10 (original): The layered composition of claim 1, wherein the Ag-containing layer has about 0.2 atom percent Cu.

Claim 11 (original): The layered composition of claim 1, wherein the Ag-containing layer is in direct contact with at least a portion of the Cu-containing ceramic superconductor.

Claim 12 (original): The layered composition of claim 1, wherein the Ag-containing layer is present as both a substrate and as a stabilizer.

Claim 13 (original): The layered composition of claim 1, wherein the Ag-containing layer is present as both a substrate layer and a stabilizing layer, both layers being in direct contact with at least a portion of the Cu-containing ceramic superconductor.

Claim 14 (currently amended): The layered composition of claim 1, wherein the Ag-containing layer is present as one or more of the a substrate and the a stabilizing layer and the a sheath.

Claim 15 (original): A biaxially or a non-biaxially aligned Ag or Ag alloy substrate layer having between about 0.1 and about 0.3 atom percent Cu directly in contact with a Cu-containing ceramic superconductor.

Claim 16 (original): The composition of claim 15, wherein the Cu-containing superconductor is a member of one or more of the YBCO family or the BS₂CCO family or the TB₂SCCO family or the HB₂SCCO family.

Claim 17 (original): The composition of claim 16, wherein a Ag or Ag alloy layer having between about 0.1 and about 0.3 atom percent Cu is a stabilizing layer and/or a sheath in contact with the Cu-containing ceramic superconductor.

Claim 18 (original): The composition of claim 17, wherein the Cu-containing ceramic superconductor is a member of the YBCO family.

Claim 19 (original): The composition of claim 18, wherein the Cu is present in the Ag or Ag alloy at about 0.2 atom percent.

Claim 20 (original): The composition of claim 19 made by the method of forming a biaxially aligned superconductor on a non-biaxially aligned substrate substantially chemically inert to the biaxially aligned superconductor comprising: providing a non-biaxially aligned substrate chemically inert to the superconductor, and depositing a biaxially aligned superconductor material directly on the non-biaxially aligned substrate.